



H3C UniServer R4700 G5 Server

2-way 1U rack server designed for intelligent computing for data center

Intel® Xeon, Enable Performance Efficiency

Release Date: April, 2024



New H3C Technologies Co., Limited

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Industrial-leading performance improves data center productivity

- Support up to 80 cores and 6TB memory
- 16 x Intel® Optane™ DC Persistent Memory Module (PMem 200)
- Support 4 High-performance GPU

Favorable Scalability and flexibility

- At most 12 Drives bays includes 8 x NVMe/SAS/SATA bays
- 4 x PCI-E 4.0 Slots + 1 OCP3.0 slot

Effective Security Design

- TPM/TCM
- Chassis Intrusion Detection
- Silicon Root of Trust

Friendly interactive management Module

- 1U LCD touchable smart management module

Highlights: High Performance High efficiency

New generation H3C UniServer R4700 G5 provide outstanding performance within 1U rack by adopting the latest Intel® X86 platform as well as several optimization for modern data center. Industrial-leading manufacturing process and system design enable customers to easily and reliably manage their IT infrastructure.

H3C UniServer R4700 G5 server is a H3C self-developed mainstream 1U rack server.

R4700 G5 utilizes the most recent 3rd Gen Intel® Xeon® Scalable processors and 8 channel DDR4 memory with 3200MT/s speed to strongly lift the performance up to 52% compared with previous platform.

Data Center Level GPU and NVMe SSD also equip with excellent IO scalability.

Maximum 96% power efficiency and 5 ~ 45°C operating temperature provide users a TCO returns in a greener data center.

R4700 G5 is optimized for environments:

- General workloads in high density data center — middle to large enterprise or cloud server provider.
- Flexible Workloads — Database, Virtualization, Private Cloud, Public Cloud.
- Computing Intensive architecture — Big Data, Business Intelligence, Geographical Exploration and Research.
- Low-latency Transaction Applications — Online interactive transaction system in finance industry.
- The R4700 G5 supports Microsoft® Windows® and Linux operating systems, as well as VMware and H3C CAS and can operate perfectly in heterogeneous IT environments.

Detailed Specification

CPU	2 x 3 rd generation Intel® Xeon® Ice Lake SP series (each processor up to 40 cores and maximum 270W power consumption)
Chipset	Intel® C621A
Memory	32 x DDR4 DIMM slots , maximum 6.0 TB Up to 3200 MT/s data transfer rate RDIMM Up to 16 Intel® Optane™ DC Persistent Memory Module PMem 200 series (Barlow Pass)
Storage controller	Embedded RAID controller Standard PCIe HBA cards and storage controllers, depending on model
FBWC	8 GB DDR4 cache, depending on model ,support supercapacitor protection
Storage	Up to Front 4LFF bays, Rear 2SFF bays* Up to Front 10SFF bays, Rear 2SFF bays* Front SAS/SATA HDD/SSD/NMVe Drives, maximum 8 x U.2 NVMe Drives SATA/PCIe M.2 SSDs, 2 x SD card kit , depending on model
Network	1 x onboard 1 Gbps management network port 1 x OCP 3.0 slot for 4 x 1GE or 2 x 10GE or 2 x 25GE NIC PCIe Standard slots for 1/10/25/40/100GE/IB Ethernet adapter,
PCIe slots	4 x PCIe 4.0 standard slots
Ports	VGA connectors (Front and Rear) and serial port (RJ-45) 5 x USB 3.0 ports (1 front, 2 rear, and 2 internal) 1 dedicated management Type-C port
GPU	4 x single-slot wide GPU modules
Optical drive	External optical disk drive, optional
Management	HDM OOB system (with dedicated management port) and H3C iFIST/FIST, support LCD touchable smart model
Security	Intelligent Front Security Bezel * Chassis Intrusion Detection TPM2.0 Silicon Root of Trust 2FA for HDM
Power supply	1+1 Redundancy power supply Titanium 850W/1600W Platinum 550W/800W/850W/1300W/1600W DC power supply Hot swappable Redundant Fans
Standards	CE, UL, FCC, VCCI, EAC, etc.
Operating temperature	5°C to 45°C (41°F to 113°F) The maximum operating temperature varies by server configuration. For more information, see the technical documentation for the device.
Dimensions (H × W × D)	1U Height Without a security bezel: 42.9 x 434.6 x 780 mm (1.69 x 17.11 x 30.71 in) With a security bezel: 42.9 x 434.6 x 808 mm (1.69 x 17.11 x 31.81 in)

*The options may be different depending on the specific requirement, refer to related user guide for detail



New H3C Technologies Co., Limited

Beijing Headquarters
Tower 1, LSH Center, 8 Guangshun South Street, Chaoyang
District, Beijing, China
Zip: 100102
Hangzhou Headquarters
No.466 Changhe Road, Binjiang District, Hangzhou, Zhejiang,
China
Zip: 310052

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